



SoundBonding application

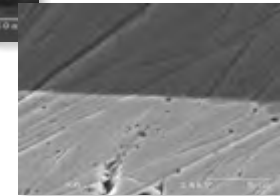
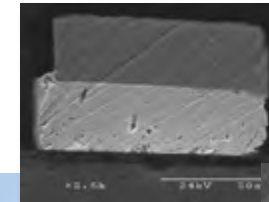
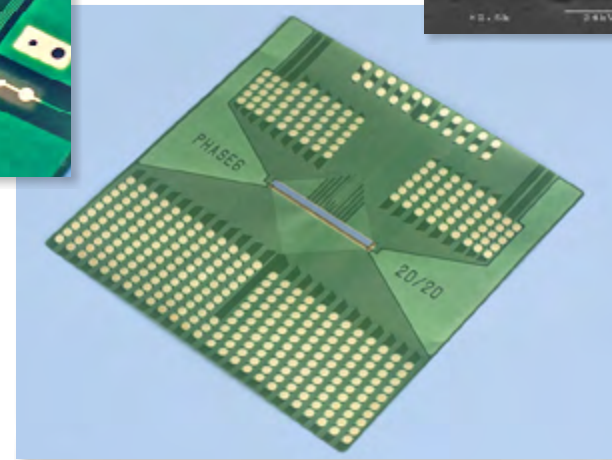
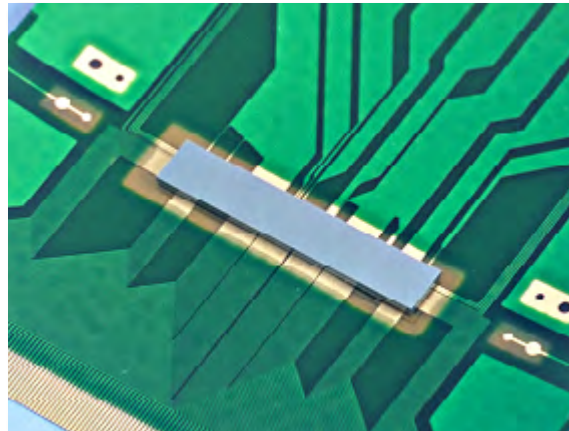


〈フリップチップ接合〉

半導体 / 多バンプ電極音波接合



SH50MPi Flip chip bonding
Semi-automatic system



(Magnified bonded cross section)

Chip size ; 20.05 x 1.06 x 0.42 mm
Chip bump ; Au plated 770 pins
Bump pitch ; 40 (30) μ m
Substrate ; Au plated pads on 2 layers of film

SoundPower[®]
Laboratory

ULTEX[®]